

MOSFET Silicon N-Channel MOS

1. Applications

For Soft Switching Boost PFC switch, HB or AHB or LLC half bridge and full bridge topologies.

Such as phase-shift-bridge(ZVS),LLC Application-Server Power, Telecom Power, EV Charging, Solar inverter.



2. Features

Low drain-source on-resistance: $R_{DS(ON)} = 0.027\Omega$ (typ.)

Easy to control Gate switching

Enhancement mode: $V_{th} = 3.2$ to 4.8 V

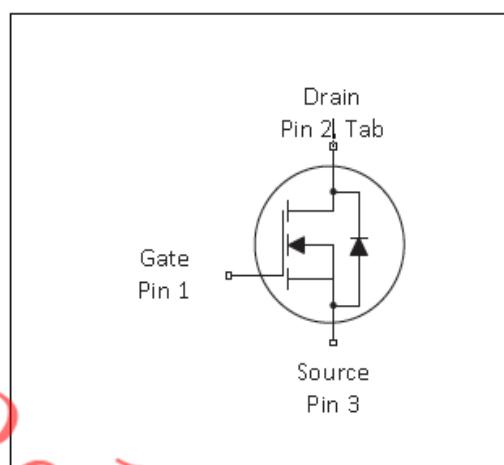
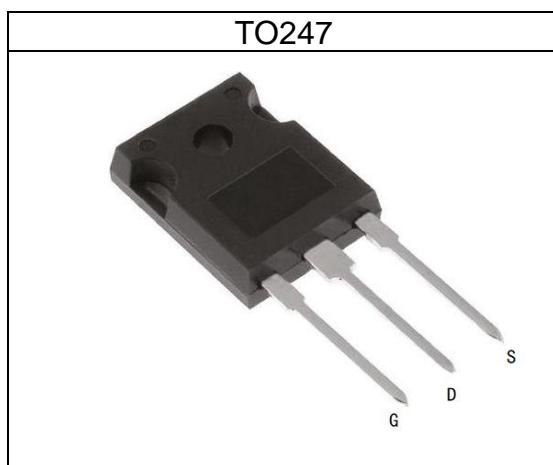


Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS} @ $T_{j,max}$	700	V
$R_{DS(on),max}$	31	$m\Omega$
$Q_{g,typ}$	150.9	nC
$I_{D,pulse}$	267	A
Body diode dv/dt	50	V/ns

3. Packaging and Internal Circuit

Part Name	Package	Marking
ASW65R031EFD	TO247	ASW65R031EFD



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1 Maximum ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D		-	89	A	$T_C=25^\circ\text{C}$
Pulsed drain current ²⁾	$I_{D,\text{pulse}}$	-	-	267	A	$T_C=25^\circ\text{C}$
Avalanche energy, single pulse	E_{AS}	-	-	414	mJ	$T_C=25^\circ\text{C}, VDD=50\text{V}, L=10\text{mH}, RG=25\Omega$
Avalanche current, single pulse	I_{AR}	-	-	9.1	A	$T_C=25^\circ\text{C}, VDD=50\text{V}, L=10\text{mH}, RG=25\Omega$
MOSFET dv/dt ruggedness	dv/dt	-	-	80	V/ns	$V_{DS}=0...400\text{V}$
Gate source voltage (static)	V_{GS}	-20	-	20	V	static;
Gate source voltage (dynamic)	V_{GS}	-30	-	30	V	AC ($f > 1 \text{ Hz}$)
Power dissipation	P_{tot}	-	-	500	W	$T_C=25^\circ\text{C}$
Storage temperature	T_{stg}	-55	-	150	°C	
Operating junction temperature	T_j	-55	-	150	°C	
Soldering Temperature Distance of 1.6mm from case for 10s	T_L			260	°C	
Reverse diode dv/dt ³⁾	dv/dt	-	-	50	V/ns	$V_{DS}=0...400\text{V}, I_{SD} \leq 45\text{A}, T_j=25^\circ\text{C}$ see table 8

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¹⁾Limited by $T_{j,\text{max}}$. Maximum Duty Cycle D = 0.50

²⁾Pulse width t_p limited by $T_{j,\text{max}}$

³⁾Identical low side and high side switch with identical RG

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.25	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	°C/W	device on PCB, minimal footprint

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3 Electrical characteristics

at $T_j=25^\circ\text{C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	655	-	-	V	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$
Gate threshold voltage	$V_{(\text{GS})\text{th}}$	3.2		4.8	V	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$
Zero gate voltage drain current	I_{DSS}	-	-	5	μA	$V_{\text{DS}}=650\text{V}, V_{\text{GS}}=0\text{V}, T_j=25^\circ\text{C}$
Gate-source leakage current	I_{GSS}	-	-	100	nA	$V_{\text{GS}}=30\text{V}, V_{\text{DS}}=0\text{V}$
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	-	0.027	0.031	Ω	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=28\text{A}, T_j=25^\circ\text{C}$
Gate resistance (Intrinsic)	R_{G}	-	3.3	-	Ω	$f=1\text{MHz}$, open drain

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	8031	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=400\text{V}, f=1\text{MHz}$
Output capacitance	C_{oss}	-	140.7	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=400\text{V}, f=1\text{MHz}$
Reverse transfer capacitance	C_{rss}	-	1.56	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=400\text{V}, f=1\text{MHz}$
Turn-on delay time	$t_{\text{d}(\text{on})}$	-	39	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=28\text{A}$ $R_{\text{G}}=3.4\Omega$
Rise time	t_{r}	-	56	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=28\text{A}$ $R_{\text{G}}=3.4\Omega$
Turn-off delay time	$t_{\text{d}(\text{off})}$	-	138	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=28\text{A}$ $R_{\text{G}}=3.4\Omega$
Fall time	t_{f}	-	7.3	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=28\text{A}$ $R_{\text{G}}=3.4\Omega$

Table 6 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	40.4	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=28\text{A}, V_{\text{GS}}=10\text{V}$
Gate to drain charge	Q_{gd}	-	54.9	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=28\text{A}, V_{\text{GS}}=10\text{V}$
Gate charge total	Q_{g}	-	150.9	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=28\text{A}, V_{\text{GS}}=10\text{V}$
Gate plateau voltage	V_{plateau}	-	5.9	-	V	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=28\text{A}, V_{\text{GS}}=10\text{V}$

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Table 7 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V_{SD}	-	0.63	-	V	$V_{GS}=0V, I_F=1A, T_j=25^\circ C$
Reverse recovery time	t_{rr}	-	182	-	ns	$V_r=400V, I_F=28A, dI/dt=100A/\mu s$
Reverse recovery charge	Q_{rr}	-	1.66	-	μC	$V_r=400V, I_F=28A, dI/dt=100A/\mu s$
Peak reverse recovery current	I_{rrm}	-	16.4	-	A	$V_r=400V, I_F=28A, dI/dt=100A/\mu s$

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4 Electrical characteristics diagram

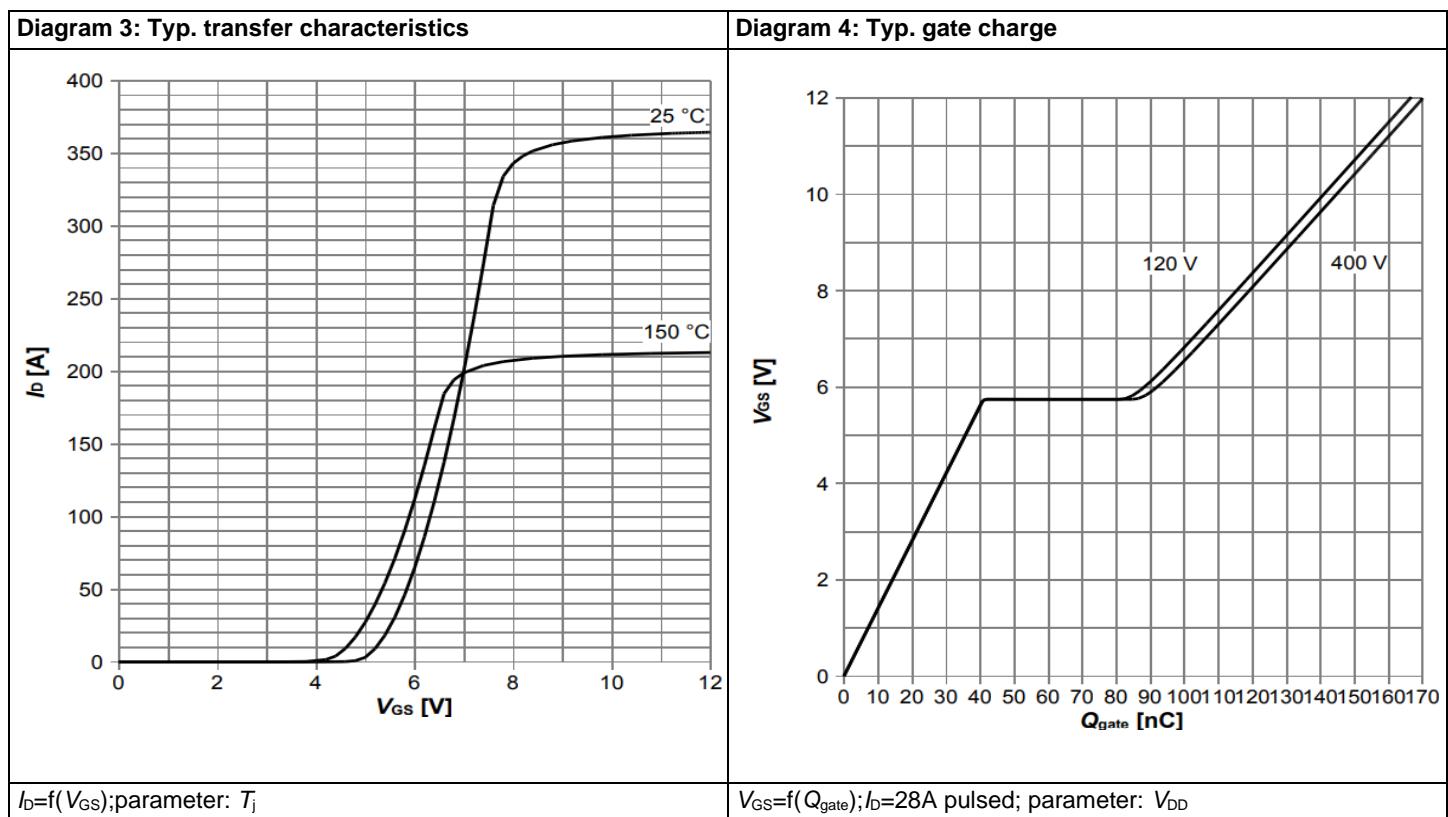
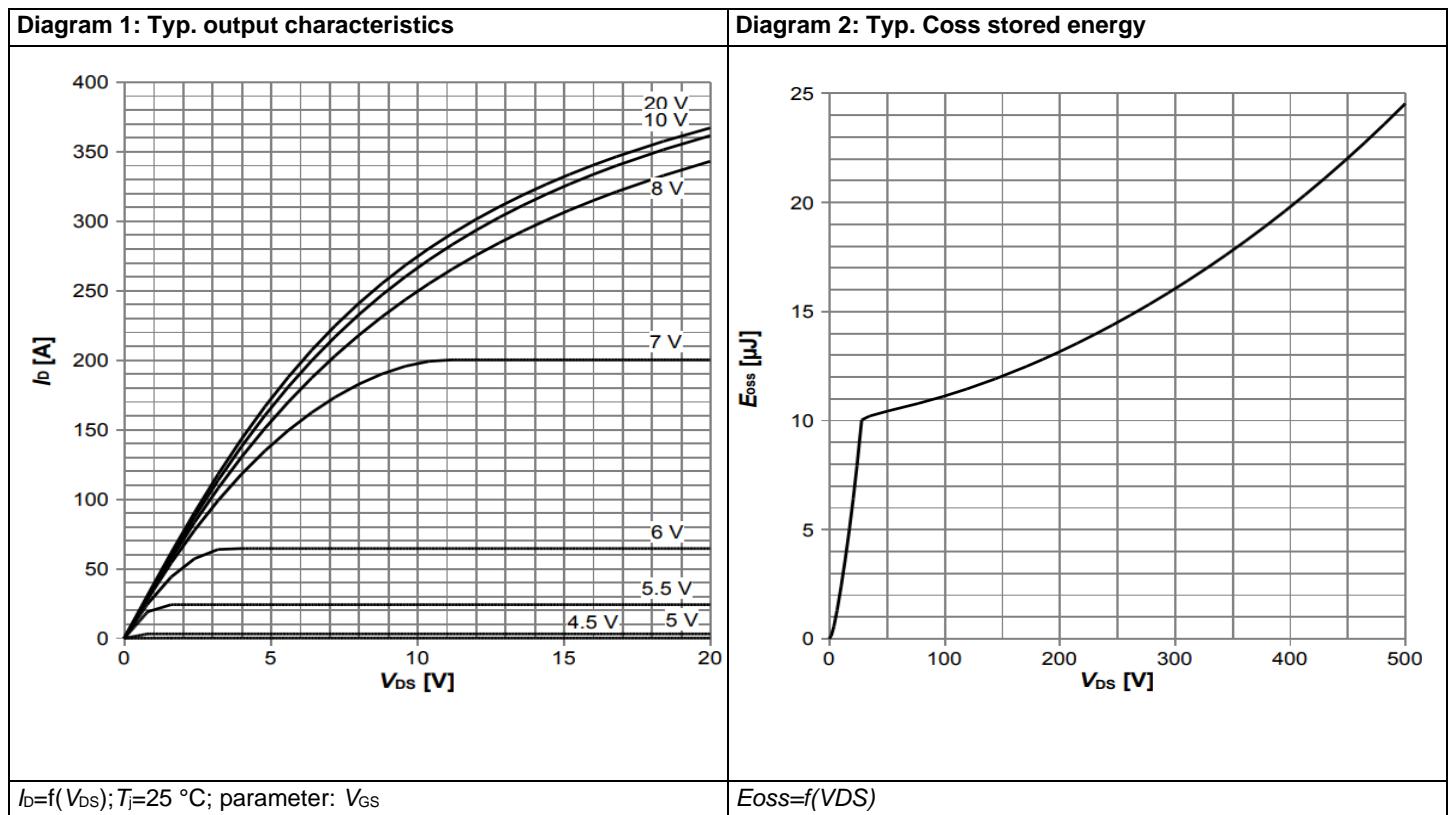
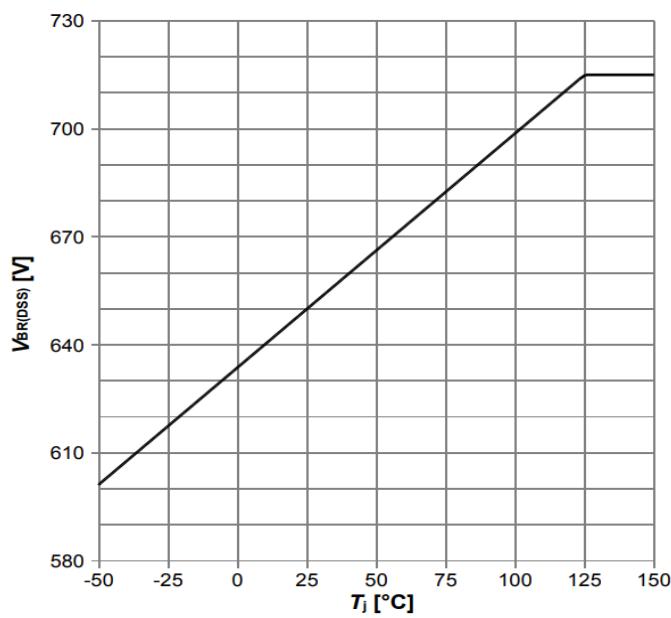
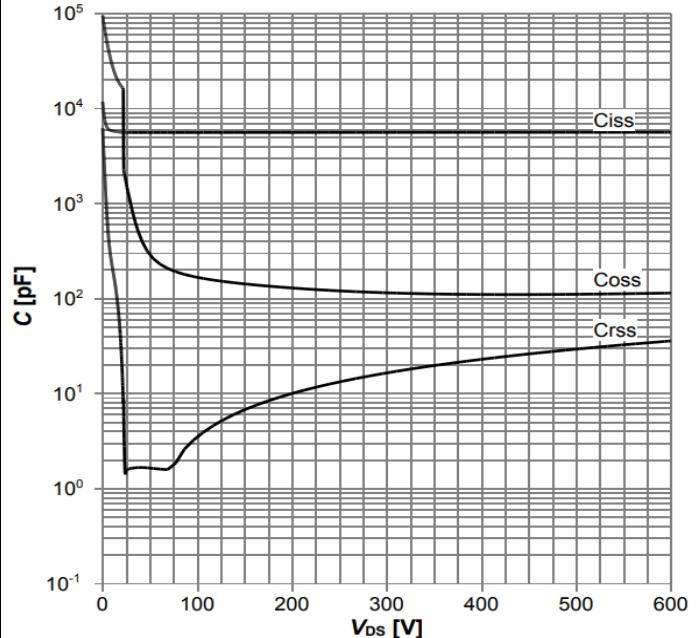
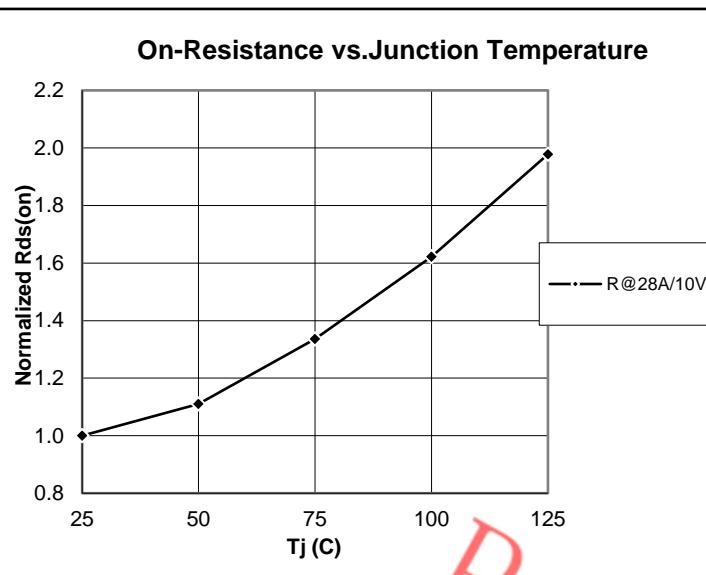
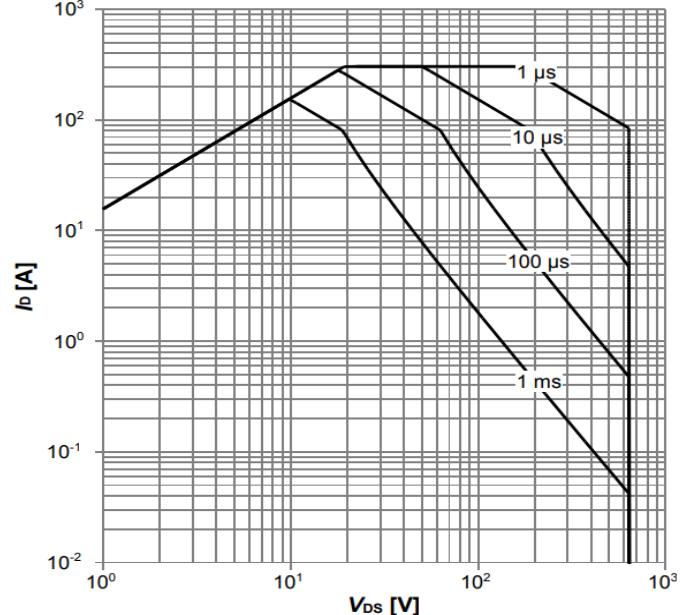
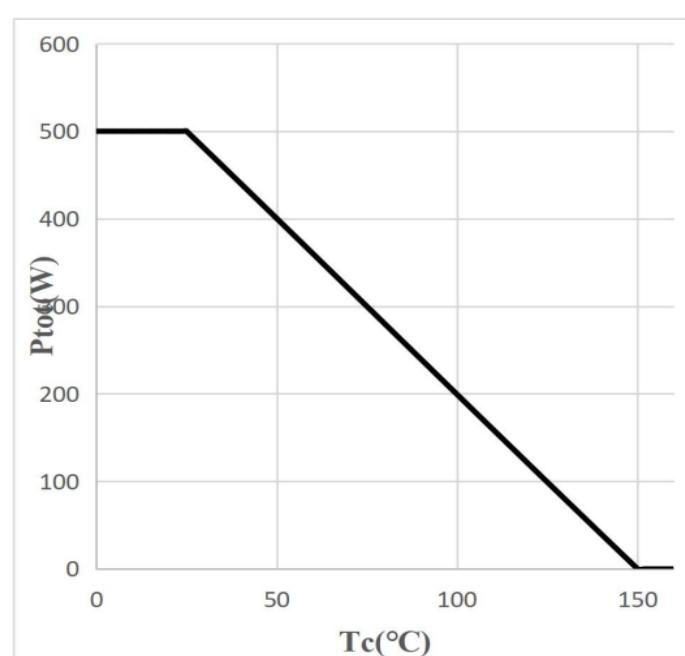


Diagram 5: Drain-source breakdown voltage

 $V_{BR(DSS)}=f(T_j); I_D=1\text{mA}$
Diagram 6: Typ. capacitances

 $C=f(V_{DS}); V_{GS}=0\text{V}; f=1\text{MHz}$
Diagram 7: Typ. On-Resistance vs. Junction Temperature

 $R_{ds(on)}=f(T_j); V_{GS}=10\text{V}/I_D=28\text{A}$
Diagram 8: Safe operating area Tc=25 °C, TO247

 $I_D=f(V_{DS}); T_c=25\text{ °C}; V_{GS}>7\text{V}; D=0; \text{parameter tp}$

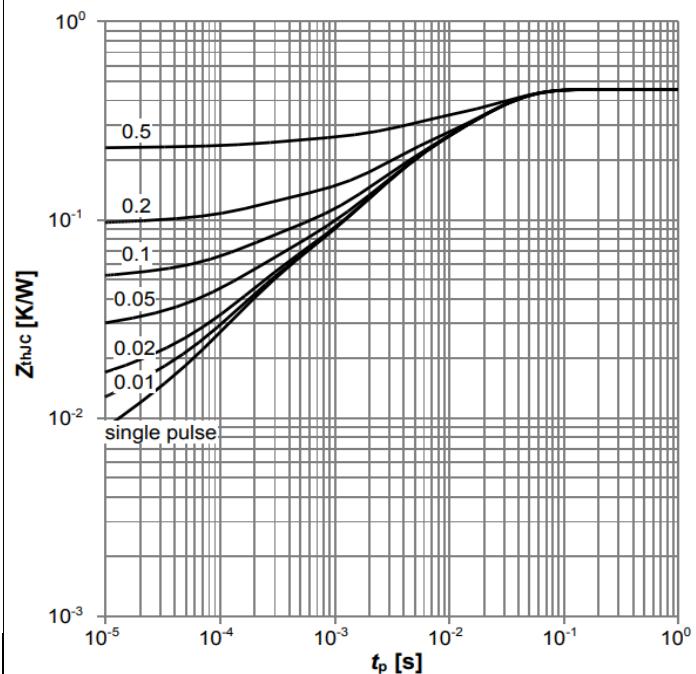
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Diagram 9: Typ. Power Dissipation



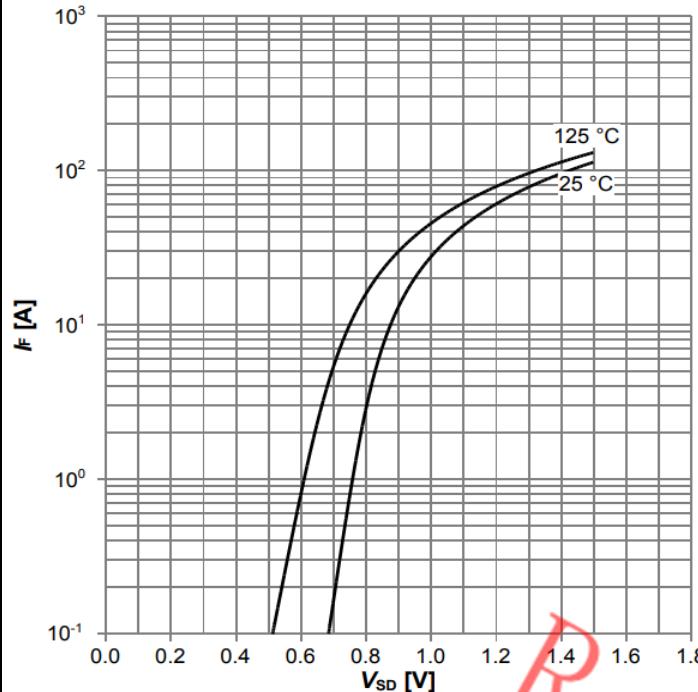
$$P_{\text{tot}} = f(T_c)$$

Diagram 10: Max. transient thermal impedance



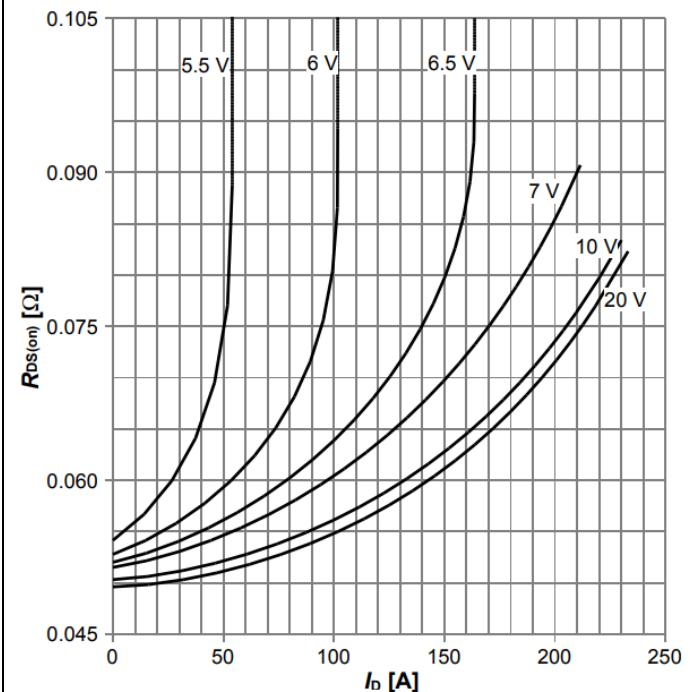
$$Z_{\text{thJC}} = f(t_p); \text{ parameter: } D = t_p/T$$

Diagram 11: Forward characteristics of reverse diode



$$I = f(V_{SD}); \text{ parameter: } T_j$$

Diagram 12: Typ. Drain-source on-state resistance



$$R_{\text{ds(on)}} = f(T_j); T_j = 125^\circ\text{C}, \text{ Parameter: } V_{\text{gs}}$$

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ASW65R031EFD

5 Test Circuits

Table 8 Diode characteristics

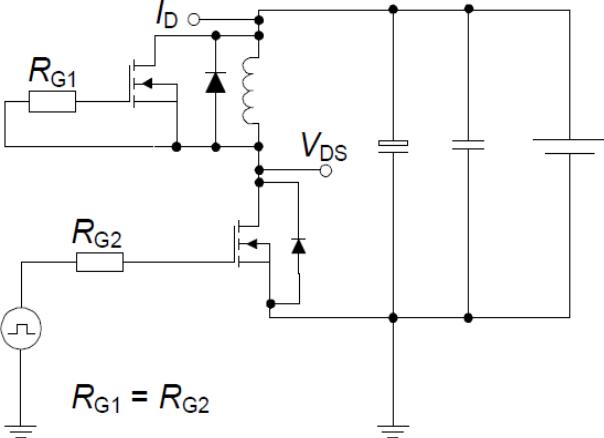
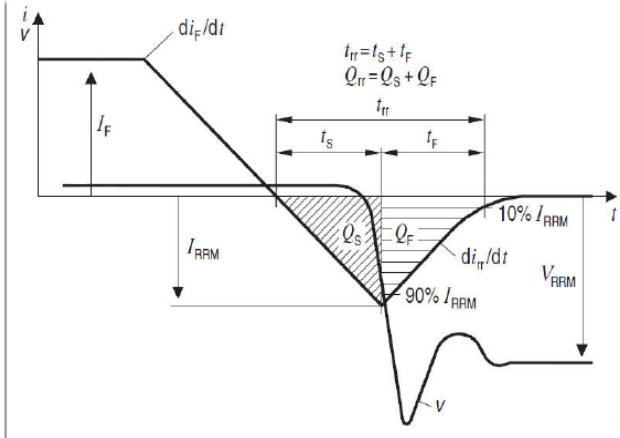
Test circuit for diode characteristics	Diode recovery waveform
 $R_{G1} = R_{G2}$	

Table 9 Switching times

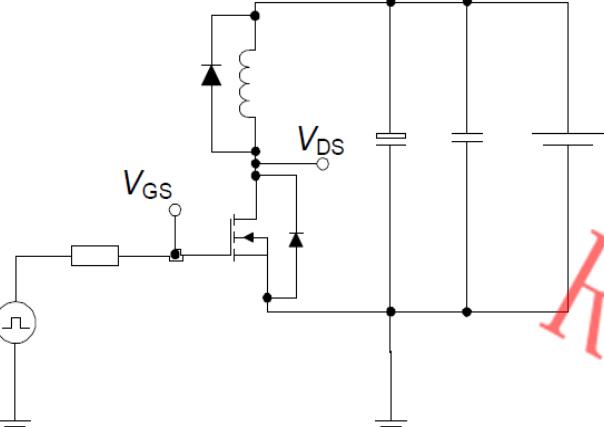
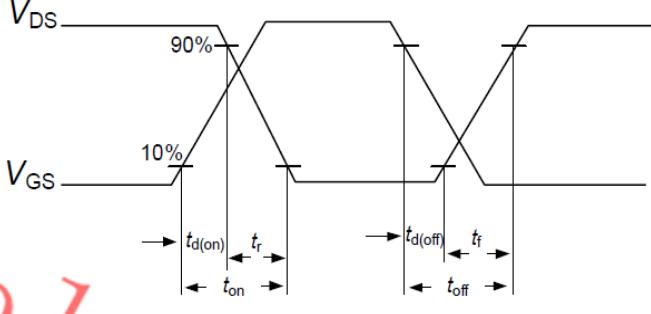
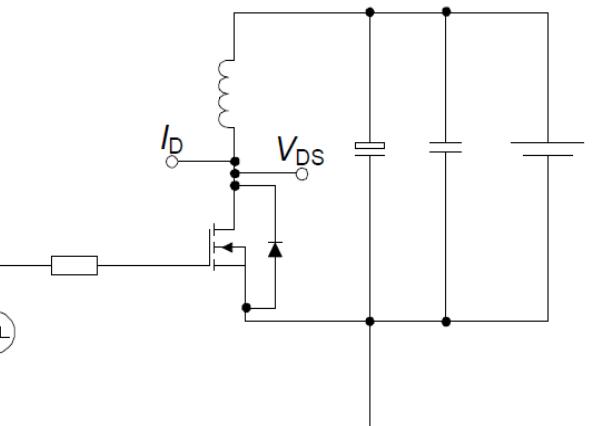
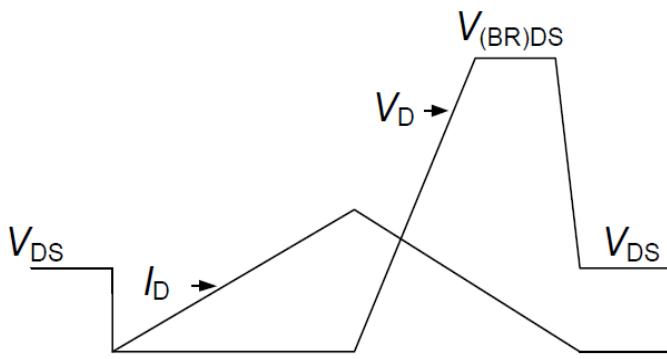
Switching times test circuit for inductive load	Switching times waveform
	

Table10 Unclamped inductive load

Unclamped inductive load test circuit	Unclamped inductive waveform
	

6 Package Outlines

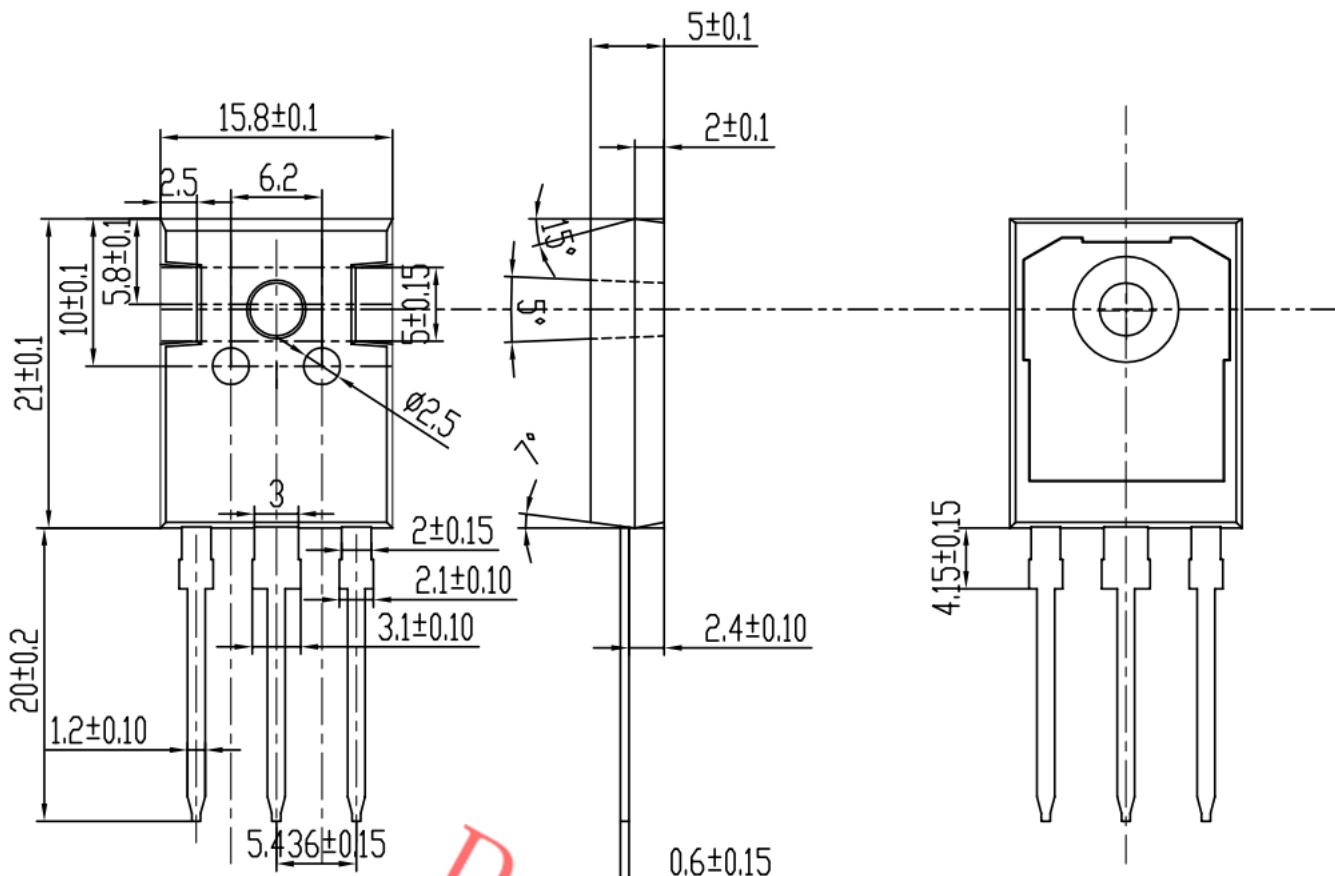


Figure: Outline PG-T0247(HT)

Revision History

Revision	Date	Subjects (major changes since last revision)
1.0	2022-12-13	Preliminary version

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